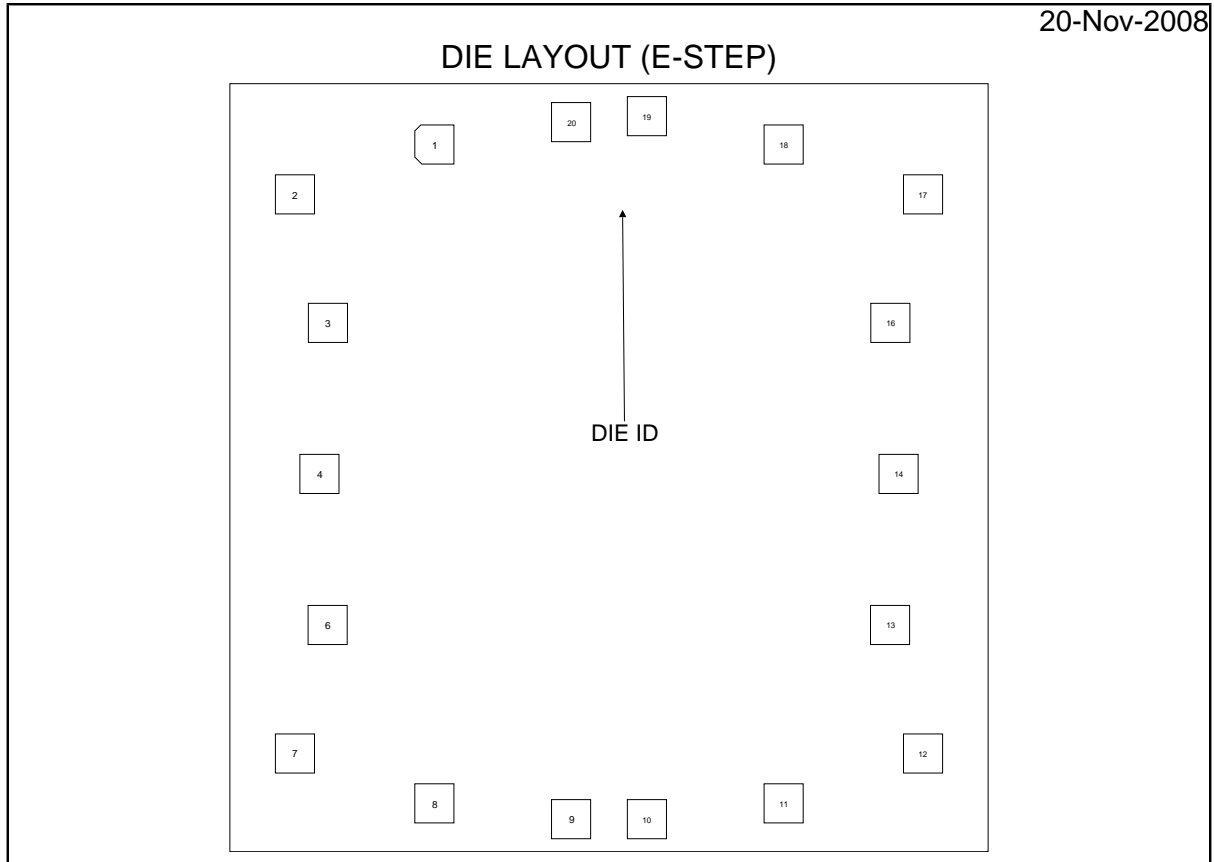


DS26C32A MD8
QUAD DIFFERENTIAL LINE RECEIVER



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	DS26C32	Bond Pad Opening Size (min)	102.18µm x 102.18µm
Die Step	E	Bond Pad Metalization	AL 1.0%SI
Physical Attributes		Passivation	PECVDOX NITRIDE
Wafer Diameter	150mm	Back Side Metal	BAREBACK
Die Size (Drawn)	1981.20µm x 2006.60µm 78.0mils x 79.0mils	Back Side Connection	GND
Thickness	330µm Nominal		
Min Pitch	198µm		

Note: All values are rounded to the nearest micron.

Special Assembly Requirements:

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Die Bond Pad Coordinate Locations(E-Step)						
(Referenced to die center, coordinates in μm) NC = No Connection, N.U. = Not Used						
Signal Name	Pad Number	X/Y Coordinates		Pad Size		
		X	Y	X	Y	
INPUTS A -	1	-456	844	102	x	102
INPUTS A +	2	-821	714	102	x	102
OUTPUT A	3	-734	378	102	x	102
ENABLE	4	-757	-16	102	x	102
OUTPUT C	6	-735	-411	102	x	102
INPUTS C +	7	-821	-747	102	x	102
INPUTS C -	8	-456	-877	102	x	102
GND	9	-99	-918	102	x	102
GND	10	99	-918	102	x	102
INPUTS D -	11	456	-877	102	x	102
INPUTS D +	12	821	-747	102	x	102
OUTPUT D	13	734	-411	102	x	102
/ENABLE	14	757	-16	102	x	102
OUTPUT B	16	735	378	102	x	102
INPUTS B +	17	821	714	102	x	102
INPUTS B -	18	456	844	102	x	102
VCC	19	99	918	102	x	102
VCC	20	-99	903	102	x	102

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QUAD DIFFERENTIAL LINE RECEIVER

Notes

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